PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16112
1.3 Title of PCN	JCAP (China) additional source for STM32H563x and STM32H573x listed products in WLCSP80 package
1.4 Product Category	STM32H563x and STM32H573x in WLCSP80 package
1.5 Issue date	2026-03-10

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	JCAP (China)

4. Description of change

	Old	New
4.1 Description	Current assembly site ASE Kaohsiung (Taiwan)	Assembly sites: - ASE Kaohsiung (Taiwan) - current Assembly sites - JCAP (China) - new assembly site
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: Marking composition change. Slight RDL topology changes around some tiny location without impacting functionalities. - Fit: No impact: - No change on WLCSP dimensions - No change on ball characteristics - Function: No impact	

5. Reason / motivation for change

5.1 Motivation	Second source introduction
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible in the marking with PP code changing - from AA : ASE KaoHsiung (Taiwan) - to GN : JCAP (China) Please refer to PCN 16112_Additional information.pdf document for further details.

7. Timing / schedule

7.1 Date of qualification results	2026-07-22
7.2 Intended start of delivery	2026-08-05
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16112 MDRF-GPAM-RER2605 PCN16112 - JCAP (China) additional source for WLCSP package - reliability plan.pdf

8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-03-10

9. Attachments (additional documentations)
16112 Public product.pdf 16112 MDRF-GPAM-RER2605 PCN16112 - JCAP (China) additional source for WLCSP package - reliability plan.pdf 16112 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32H563MIY3QTR	
	STM32H573MIY3QTR	

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